

REMARKS

Favorable reconsideration of this application, as presently amended and in light of the following discussion, is respectfully requested.

Claims 1-14 are currently pending, with Claims 4-6 and 10-12 being withdrawn from consideration as directed to a non-elected invention. Claims 1, 4, 7, and 10 have been amended by the present amendment. The changes to the claims are supported by the originally filed specification and do not add new matter.¹

In the outstanding Office Action, Claims 1-3 and 13 were rejected under 35 U.S.C. § 102(e) as being anticipated by U.S. Patent No. 6,807,064 to Hedler et al. (hereinafter “the ‘064 patent”); and Claims 7-9 and 14 were rejected under 35 U.S.C. § 103(a) as being unpatentable over the ‘064 patent in view of U.S. Patent Application Publication No. 2001/0020985 to Hinata (hereinafter “the ‘985 patent”).

Amended Claim 1 is directed to a multilayer wired board including at least part of an electrical circuit board in which a plurality of wired boards are stacked so as to face their wired surfaces toward each other, comprising:

electrical connection parts between said wired boards are connected through a first end of an elastic conductive material part adhered to a first wired board, and a second end of the elastic conductive material part in contact with a second wired board;

a double-sided adhesive material part is provided between the plurality of wired boards to adhere them together, and an opening is formed in the double-sided adhesive material part so as to surround at least part of a peripheral edge portion of said elastic conductive material part to seal said plurality of wired boards;

wherein a height of said double-sided adhesive material part is smaller than a height of said elastic conductive material part, and

¹ See, e.g., page 13, line 18 to page 14, line 10 of Applicants’ specification.

the second end of the elastic conductive material part
and a peripheral part of the second wired board are bent and
pressed together.

Regarding the rejection of Claim 1 under 35 U.S.C. § 102(e), the '064 patent is directed to an electronic component with at least one semiconductor chip and method for producing the electronic component. In particular, the '064 patent discusses that each of the flexible contacts 10 contains a flat conductor track segment, which yields elastically to vertical pressure. Further, the '064 patent discusses a curved portion 11 that is parallel in some segments to the surface of the rewiring layer 2 is rounded in such a way that the resilient contact 10, upon being placed on a contact face 20 can slide easily along the contact face 20.²

However, it is respectfully submitted that the '064 patent fails to disclose that a height of said double-sided adhesive material part is smaller than a height of said elastic conductive material part. Rather, the '064 patent discusses an intermediate layer 12 that has a plurality of recesses, in which flexible contacts 10 are located when the intermediate layer 12 has been applied to a rewiring layer 2. The '064 patent discusses that on the side toward the semiconductor chip 1 and the rewiring layer 2, the intermediate layer 12 is covered by a first adhesive layer 14. Further, the '064 patent discusses that on its opposite surface, the intermediate layer 12 is covered with a second adhesive layer 16.³ The '064 application does not disclose that ***a height of the double-sided adhesive material part (i.e., the intermediate layer 12, first adhesive layer 14, and second adhesive layer 16) is made smaller than a height of said elastic conductive material part (i.e., the intermediate layer 9 and contacts 10).***

Further, it is respectfully submitted that the '064 patent fails to disclose that the second end of the elastic conductive material part and a peripheral part of the second wired board are bent and pressed together. Rather, the '064 patent simply discusses that a printed

² See '064 patent, column 7, lines 1-7.

³ Id. at column 7, lines 19-30.

circuit board 18 is provided with contact faces 20 corresponding to curved portions 11 of the flexible contacts 10 and that, when the rewiring layer 2 is put in place, establish an electrical contact with the rewiring layer and thus with the semiconductor chip.⁴ The '064 patent does not disclose that ***the second end*** of the elastic conductive material part ***and a peripheral part*** of the second wired board ***are bent and pressed together.***

Accordingly, it is respectfully submitted that the rejection of Claim 1 (and all associated dependent claims) as being anticipated by the '064 patent is rendered moot by the present amendments to Claim 1.

Regarding the rejection of Claim 7 under 35 U.S.C. § 103(a), Claim 7 recites limitations analogous to the limitations recited in Claim 1. Further, Claim 7 has been amended in a manner analogous to the amendments to Claim 1. Moreover, it is respectfully submitted that the '985 application fails to remedy the deficiencies of the '064 patent, as discussed above. Accordingly, for reasons analogous to the reasons stated above for the patentability of Claim 1, it is respectfully submitted that the rejection of Claim 7 (and all associated dependent claims) as being unpatentable over the '064 patent and the '985 application is rendered moot by the present amendments to Claim 7.

Thus, it is respectfully submitted that independent Claims 1 and 7 (and all associated dependent claims) patentably define over any proper combination of the '064 patent and the '985 application.

⁴ See '064 patent, column 7, lines 31-36.

Consequently, in view of the present amendment and in light of the above discussion, the outstanding grounds for rejection are believed to have been overcome. The application as amended herewith is believed to be in condition for formal allowance. An early and favorable action to that effect is respectfully requested.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.



Bradley D. Lytle
Attorney of Record
Registration No. 40,073

Johnny Ma
Registration No. 59,976

Customer Number

22850

Tel: (703) 413-3000
Fax: (703) 413 -2220
(OSMMN 03/06)

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